


Date: 4/26/2021

Material Number: SI8282CD-ISR

Pkg Config.: PK0977

Detailed Device Composition 									
No.	Homogeneous Material	Material Weight (mg)	Material Content	CAS Number	Material Weight (%)	Material Weight (mg)	ppm of Material	Wt % of Total Unit	ppm of Total Unit
1	Mold Compound	450.28	Carbon Black	1333-86-4	0.300	1.351	3000	0.2115	2115
			Epoxy Resin (Proprietary)	Proprietary	8.000	36.022	80000	5.6412	56412
			Phenol Resin (Proprietary)	Proprietary	5.700	25.666	57000	4.0193	40193
			Silicon Dioxide	60676-86-0	86.000	387.241	860000	60.6428	606428
2	Leadframe	185.51	Copper	7440-50-8	96.190	178.442	961900	27.9444	279444
			Gold	7440-57-5	0.020	0.037	200	0.0058	58
			Iron	7439-89-6	2.250	4.174	22500	0.6537	6537
			Nickel	7440-02-0	1.250	2.319	12500	0.3631	3631
			Palladium	7440-05-3	0.050	0.093	500	0.0145	145
			Phosphorous	7723-14-0	0.100	0.186	1000	0.0291	291
			Silver	7440-22-4	0.020	0.037	200	0.0058	58
			Zinc	7440-66-6	0.120	0.223	1200	0.0349	349
3	Die Attach Epoxy	0.44	2-Ethylhexyl Glycidyl Ether	2461-15-6	7.000	0.031	70000	0.0048	48
			Bisphenol F	620-92-8	12.000	0.053	120000	0.0083	83
			Epoxy Acrylate	15625-89-5	15.000	0.066	150000	0.0103	103
			Silver	7440-22-4	65.000	0.286	650000	0.0448	448
			Substituted Polyamine	68490-66-4	1.000	0.004	10000	0.0007	7
4	Bond Wire	0.63	Gold	7440-57-5	99.000	0.624	990000	0.0977	977
			Palladium	7440-05-3	1.000	0.006	10000	0.0010	10
5	Die	0.89	Aluminum	7429-90-5	0.163	0.001	1630	0.0002	2
			Copper	7440-50-8	0.001	0.000	10	0.0000	0
			Silicon	7440-21-3	99.726	0.888	997260	0.1390	1390
			Tungsten	7440-33-7	0.110	0.001	1100	0.0002	2
6	Die	0.81	Aluminum	7429-90-5	0.163	0.001	1630	0.0002	2
			Copper	7440-50-8	0.001	0.000	10	0.0000	0
			Silicon	7440-21-3	99.726	0.808	997260	0.1265	1265
			Tungsten	7440-33-7	0.110	0.001	1100	0.0001	1
	Total Unit Weight =	638.56				638.56		100.0000	1000000